



Thermal Transtech International Corporation

Company profile

Thermal Transtech International Corporation (TTIC) was founded in 1998. The company is specialized in Aluminum and Copper products manufacturing & design, especially in heat sinks, heat pipes(column) heat sink cooling solution,. Over 6 years of experience, TTIC is now the famous in heat sink manufacturing & design in the world.

The company has an excellent reputation in quality control and production capacity. This reputation is achieved by combining a strong R&D team, the total quality control concept, and an integrated operation procedure.

In 2002, TTIC teamed up with Sunnet Company again for heat column research. In order to enhance the heat column technology and solve the thermal dissipate problem, TTIC cooperated with Sunnet Company to develop the heat column. Expected to bring out to the production in early 2004. TTIC will scale new heights in the thermal technology with the success of this project.

Recently, TTIC goes into the desktop thermal industry aggressively, combined the heat column and stacked fin heat sink to apply to desktop CPU cooler.

Now, TTIC is on the way to achieve the goal "being a player in the international market of heat transfer devices" We believe that with our endless effort, the goal will become reality.

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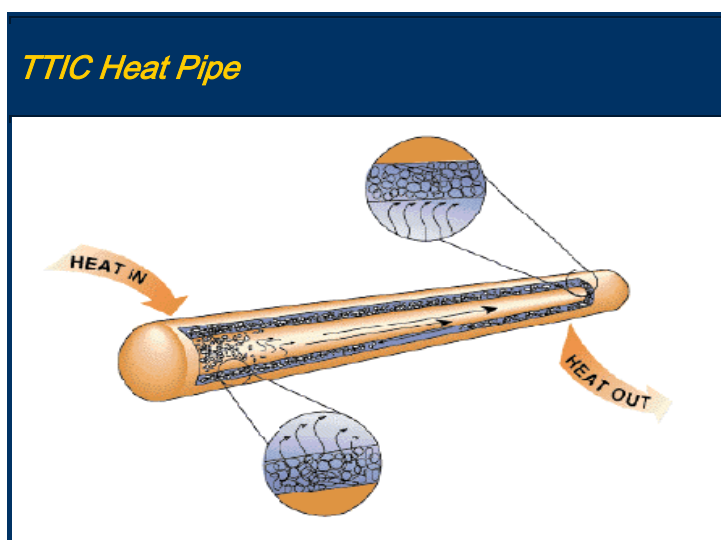
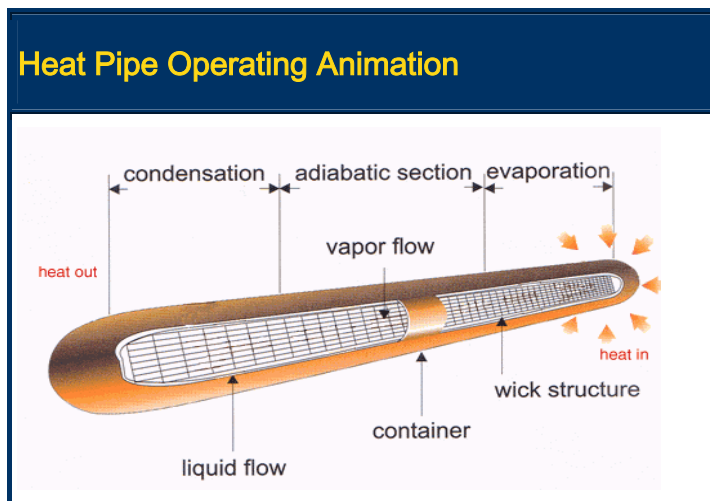
TTIC Heat Pipe

A efficient heat pipe system can be affected by length of a heat pipe, type of fluid in a heat pipe, return wick type, and the number of bends in a heat pipe.

TTIC heat pipe technology has been applied to computer cooling for years. We provide an ideal, cost effective heat pipe solution. Its small, compact profile and light weight allow it to meeting the demanding requirements of computer.

Sintered Powder

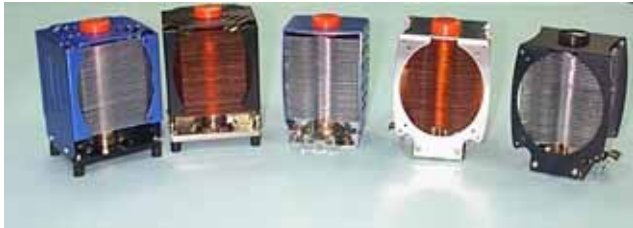
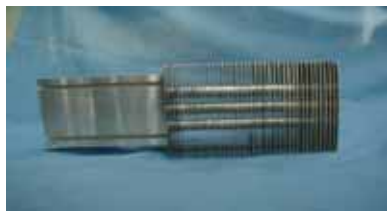
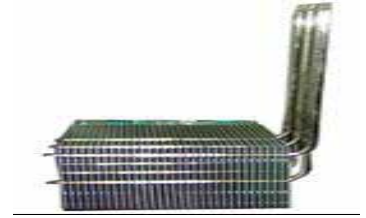
This process will provide high power handling, low temperature gradients and high capillary forces for anti-gravity applications. The photograph shows a complex sintered wick with several vapor channels and small arteries to increase the liquid flow rate. Very tight bends in the heat pipe can be achieved with this type of structure.



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Heat pipe application :

Solar heater, IGBT radiator
Enclosure cabin exchanger
Laptop module, CPU cooler
Telecom dissipate cooling



TTIC NPH SERIES CPU COOLER



HEAT COLUMN SERIES



TTIC NPH SERIES CPU COOLERS TEST REVIEWS :

<http://www.pclab.pl/art7523.html> ; <http://www.frostytech.com/articleview.cfm?articleID=1464> ;

<http://www.overclockers.com/articles754/> ; <http://www.overclockers.com/articles757/>

http://www.dansdata.com/coolercomp_p5.htm#ttnph2

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